

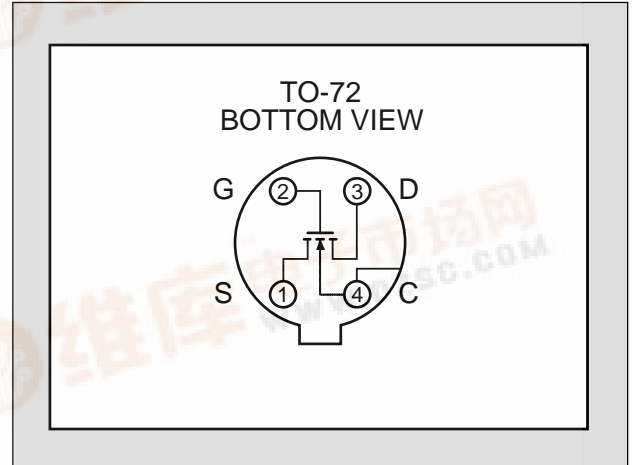
**LINEAR SYSTEMS**

*Linear Integrated Systems*

**3N170 3N171**

**N-CHANNEL MOSFET  
ENHANCEMENT MODE**

FEATURES	
Direct Replacement for INTERSIL 3N170 & 3N171	
LOW DRAIN TO SOURCE RESISTANCE	$r_{ds(on)} \leq 200\Omega$
FAST SWITCHING	$t_{d(on)} \leq 3.0ns$
ABSOLUTE MAXIMUM RATINGS <sup>1</sup>	
@ 25 °C (unless otherwise stated)	
Maximum Temperatures	
Storage Temperature	-65 to +150 °C
Operating Junction Temperature	-55 to +135 °C
Maximum Power Dissipation	
Continuous Power Dissipation	300mW
Maximum Current	
Drain to Source	30mA
Maximum Voltages	
Drain to Gate	±35V
Drain to Source	25V
Gate to Source	±35V



\* Body tied to Case.

**ELECTRICAL CHARACTERISTICS @ 25 °C (unless otherwise stated) ( $V_{SB} = 0V$  unless otherwise stated)**

SYMBOL	CHARACTERISTIC	MIN	TYP	MAX	UNITS	CONDITIONS
$BV_{DSS}$	Drain to Source Breakdown Voltage	25			V	$I_D = 10\mu A, V_{GS} = 0V$
$V_{DS(on)}$	Drain to Source "On" Voltage			2.0		$I_D = 10mA, V_{GS} = 10V$
$V_{GS(th)}$	Gate to Source Threshold Voltage	3N170	1.0	2.0		$V_{DS} = 10V, I_D = 10\mu A$
		3N171	1.5	2.0		
$I_{GSS}$	Gate Leakage Current			10	pA	$V_{GS} = -35V, V_{DS} = 0V$
$I_{DSS}$	Drain Leakage Current "Off"			10	nA	$V_{DS} = 10V, V_{GS} = 0V$
$I_{D(on)}$	Drain Current "On"	10			mA	$V_{GS} = 10V, V_{DS} = 10V$
$g_{fs}$	Forward Transconductance	1000			$\mu S$	$V_{DS} = 10V, I_D = 2.0mA, f = 1.0kHz$
$r_{ds(on)}$	Drain to Source "On" Resistance			200	$\Omega$	$V_{GS} = 10V, I_D = 0A, f = 1.0kHz$
$C_{rss}$	Reverse Transfer Capacitance			1.3	pF	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$
$C_{iss}$	Input Capacitance			5.0		$V_{DS} = 10V, V_{GS} = 0V, f = 1.0MHz$
$C_{db}$	Drain to Body Capacitance			5.0		$V_{DB} = 10V, f = 1.0MHz$

